

08-02-2000

U.S. DEPARTMENT OF COMMERCE



101421465

I COVER SHEET

ONLY

Patent and Trademark Office
Docket No. 360842006100

7.19.00

JCS98 U.S. P. 09/619536 07/19/00

To the Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

1. Eisuke WADAHARA
2. Kenichi YOSHIOKA
3. Soichi ISHIBASHI

- ☒ Individual(s) ☐ Association
☐ General Partnership ☐ Limited Partnership
☐ Corporation-State ☐ Other

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies):

Name: Toray Industries, Inc.
 Address: 2-1 Nihonbashi-Muromachi 2-chome
 Chuo-ku, Tokyo 103-8666 JAPAN

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other:

Execution Date: July 6, 2000 and July 10, 2000

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: July 6, 2000 and July 10, 2000

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

09619536

5. Name and address of party to whom correspondence concerning document should be mailed:

Barry E. Bretschneider
 Morrison & Foerster LLP
 2000 Pennsylvania Avenue, N.W.
 Washington, D.C. 20006-1888

6. Total number of applications and patents involved: 1

7. Total fee (37 C.F.R. § 3.41): \$40.00

- ☒ Enclosed
☐ Authorized to be charged to deposit account, referencing
 Attorney Docket 360842006100

8. Deposit account number: 03-1952

The Commissioner is hereby authorized to charge any fees under 37 C.F.R. § 1.21 that may be required by this paper, or to credit any overpayment to Deposit Account No. 03-1952**DO NOT USE THIS SPACE**

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Name: Barry E. Bretschneider
 Registration No: 28,055

Signature

Date

07/31/2000 BALEXAND 00000038 09619536

03 FC:581

40-00.00

Total number of pages comprising cover sheet, attachments and document: 3

Mail documents to be recorded with required cover sheet information to:

U.S. Patent and Trademark Office
 Office of Public Records
 Box Assignments
 Crystal Gateway 4, Room 335
 Washington, D.C. 20231

dc-217758

PATENT
REEL: 010954 FRAME: 0147

ASSIGNMENT

WHEREAS, We, Eisuke WADAHARA, a citizen of Japan, residing at Toray Seto-ryo 413, 1456, Tsutsui, Masaki-cho, Iyo-gun, Ehime 791-3120 Japan; Kenichi YOSHIOKA, a citizen of Japan residing at 8-9, Yunoyama 3-chome, Matsuyama-shi, Ehime 791-3120 Japan and Soichi ISHIBASHI, a citizen of Japan, residing at Famille Yogo 102, 3-31, Yogo Nishi 5-chome, Matsuyama-shi, Ehime 790-0046 Japan (hereinafter referred to as the undersigned), having made an invention entitled THERMOPLASTIC RESIN COMPOSITION, MOLDING MATERIAL, AND MOLDET ARTICLE THEREOF the undersigned executed an application for Letters Patent of the United States of America,

WHEREAS, Toray Industries, Inc., a corporation of Japan, with offices at 2-1 Nihonbashi-Muromachi 2-chome, Chuo-ku, Tokyo 103-8666 Japan (hereinafter referred to as assignee), is desirous of acquiring the entire right, title and interest in said invention, said application and all letters patent issuing for said invention,

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and of other good and valuable consideration, receipt of which is hereby acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee the entire right, title and interest, for the United States of America, its territories and possessions, and for all foreign countries, in said invention, including said patent application, all divisions and continuations thereof, all rights to claim priority based thereon, all rights to file foreign applications on said invention, and all letters patent and reissues thereof, issuing for said invention the United States of America and in any and all foreign countries.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the undersigned has knowledge or possession relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the assignee, and to execute all instruments proper to carry out the intent of this instrument. If the undersigned includes more than one individual, these obligations shall apply to all of the undersigned both individually and collectively.

The rights and property herein conveyed by the undersigned are free and clear of any encumbrance.

EXECUTED on July 6, 2000, at Seattle, Washington

Witnesses:

The Undersigned:

Eisuke WADAHARA

Kenichi Yoshiooka
Kenichi YOSHIOKA

Soichi ISHIBASHI

ASSIGNMENT

WHEREAS, We, Eisuke WADAHARA, a citizen of Japan, residing at Toray Seto-ryo 413, 1456, Tsutsui, Masaki-cho, Iyo-gun, Ehime 791-3120 Japan; Kenichi YOSHIOKA, a citizen of Japan residing at 8-9, Yunoyama 3-chome, Matsuyama-shi, Ehime 791-3120 Japan and Soichi ISHIBASHI, a citizen of Japan, residing at Famille Yogo 102, 3-31, Yogo Nishi 5-chome, Matsuyama-shi, Ehime 790-0046 Japan (hereinafter referred to as the undersigned), having made an invention entitled THERMOPLASTIC RESIN COMPOSITION, MOLDING MATERIAL, AND MOLDET ARTICLE THEREOF the undersigned executed an application for Letters Patent of the United States of America,

WHEREAS, Toray Industries, Inc., a corporation of Japan, with offices at 2-1 Nihonbashi-Muromachi 2-chome, Chuo-ku, Tokyo 103-8666 Japan (hereinafter referred to as assignee), is desirous of acquiring the entire right, title and interest in said invention, said application and all letters patent issuing for said invention,

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and of other good and valuable consideration, receipt of which is hereby acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee the entire right, title and interest, for the United States of America, its territories and possessions, and for all foreign countries, in said invention, including said patent application, all divisions and continuations thereof, all rights to claim priority based thereon, all rights to file foreign applications on said invention, and all letters patent and reissues thereof, issuing for said invention the United States of America and in any and all foreign countries.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the undersigned has knowledge or possession relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the assignee, and to execute all instruments proper to carry out the intent of this instrument. If the undersigned includes more than one individual, these obligations shall apply to all of the undersigned both individually and collectively.

The rights and property herein conveyed by the undersigned are free and clear of any encumbrance.

EXECUTED on July 10, 2000, at Iyo-gun, Ehime

Witnesses:

The Undersigned:

Eisuke Wadahara
Eisuke WADAHARA

Kenichi Yoshioka
Kenichi YOSHIOKA

Soichi Ishibashi
Soichi ISHIBASHI

10775338196

JUL 19 2000 13:23
RECORDED: 07/19/2000

PATENT GE. 07
REEL: 010954 FRAME: 0149